



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20120822001**  
**Qualification of Mold Compound 4211471 and Mount Compound 4211470**  
**for Select Devices Assembled in TI-Malaysia and TI-Taiwan**  
**using TSSOP package**  
**Change Notification / Sample Request**

**Date:** 9/3/2012  
**To:** Newark PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services  
Phone: +1(214) 480-6037  
Fax: +1(214) 480-6659

**20120822001**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
74ACT16244DGGR	null
AM26C31IPW	null
CD14538BPW	null
CD40106BPWR	null
CD40109BPWR	null
CD4011BPWR	null
CD4013BPWR	null
CD4043BPWR	null
CD4053BPWRG3	null
CD4060BPWR	null
CD4504BPWR	null
CD4541BPWR	null
CD74HC123PWR	null
CD74HC194PWR	null
CD74HC238PWR	null
CD74HC4024PWR	null
CD74HC4046APWR	null
CD74HC4051PWR	null
CD74HC4052PWR	null
CD74HC4053PWR	null
CD74HCT4053PWR	null
CY74FCT16827ATPACT	null
LM2901PW	null
LM2902PWR	null
LM311PWR	null
LM324APWR	null
LM339APWR	null
LM339PW	null
LM385BPWR-1-2	null
LM385PW-1-2	null
LM393APWR	null
LMV339IPW	null
LMV934IPW	null
LMV934IPWR	null
MAX202IPW	null
MAX3221CPW	null
MAX3221CPWR	null
MAX3221ECPW	null
MAX3221EIPW	null
MAX3221EIPWR	null
MAX3221IPW	null

MAX3221IPWR	null
MAX3222CPW	null
MAX3222CPWR	null
MAX3222ECPWR	null
MAX3222EIPW	null
MAX3222IPWR	null
MAX3223CPWR	null
MAX3223ECPW	null
MAX3223IPWR	null
MAX3232CPW	null
MAX3232CPWR	null
MAX3232ECPW	null
MAX3232EIPW	null
MAX3232IPW	null
MAX3232IPWR	null
MAX3237ECPWR	null
MAX3238IPW	null
MAX3243CPWR	null
MAX3243ECPW	null
MAX3243EIPW	null
MAX3243EIPWR	null
MAX3243IPW	null
MAX3243IPWR	null
P82B96PWR	null
PCA9518PW	null
PCA9535PW	null
PCA9535PWR	null
PCA9538PW	null
PCA9539PWR	null
PCA9543APW	null
PCA9544APWR	null
PCA9545APW	null
PCA9546APW	null
PCA9546APWR	null
PCA9548APW	null
PCA9548APWR	null
PCA9555PWR	null
PCF8574PWR	null
PCF8575PW	null
RC4560IPW	null
SN65C3221EPWR	null
SN65C3221PW	null
SN65C3221PWR	null
SN74ABT125PWR	null
SN74ABT162244DGGR	null
SN74AC04PW	null
SN74AC74PW	null
SN74AC74PWR	null
SN74ACT14PWR	null
SN74ACT244PWR	null
SN74ACT245PWR	null

SN74ACT373PWR	null
SN74ACT574PWR	null
SN74AHC08PW	null
SN74AHC123APWR	null
SN74AHC125PW	null
SN74AHC125PWR	null
SN74AHC14PW	null
SN74AHC14PWR	null
SN74AHC244PW	null
SN74AHC245PWR	null
SN74AHC32PW	null
SN74AHC373PW	null
SN74AHC541PWR	null
SN74AHC573PWR	null
SN74AHC595PWR	null
SN74AHCT240PWR	null
SN74AHCT244PW	null
SN74AHCT541PW	null
SN74AHCT541PWR	null
SN74AHCT595PWR	null
SN74ALVC08PWR	null
SN74ALVC164245DGGR	null
SN74ALVC244PW	null
SN74ALVCH162260GR	null
SN74ALVCH162373GR	null
SN74ALVCH16245DGGR	null
SN74ALVTH16244GR	null
SN74AUC16374DGGR	null
SN74AVC16244DGGR	null
SN74AVC16T245DGGR	null
SN74AVC4T245PWR	null
SN74AVC4T774PW	null
SN74AVC6T622PWR	null
SN74AVC8T245PW	null
SN74AVC8T245PWR	null
SN74AVCA164245GR	null
SN74AVCB164245GR	null
SN74AVCH8T245PWR	null
SN74CB3Q16244DGGR	null
SN74CB3Q3125PWR	null
SN74CB3Q3257PWR	null
SN74CB3Q3345PWR	null
SN74CB3T16210DGGR	null
SN74CB3T16211DGGR	null
SN74CB3T3245PW	null
SN74CBT16212CDGGR	null
SN74CBT3245CPWR	null
SN74CBTD3384PWR	null
SN74CBTD3861PWR	null
SN74CBTLV16212GR	null
SN74CBTLV3125PWR	null

SN74CBTLV3245APWR	null
SN74CBTLV3257PWR	null
SN74CBTLV3384PWR	null
SN74HC00PW	null
SN74HC02PWR	null
SN74HC138PWR	null
SN74HC14PW	null
SN74HC14PWR	null
SN74HC164PWR	null
SN74HC165PWR	null
SN74HC244PW	null
SN74HC244PWR	null
SN74HC365PWTE4	null
SN74HC541PWR	null
SN74HC573APWR	null
SN74HCT138PWR	null
SN74HCT245PWR	null
SN74HCT273PW	null
SN74LV06APWR	null
SN74LV07APWR	null
SN74LV123APWR	null
SN74LV125APWR	null
SN74LV14APWR	null
SN74LV165APWRG3	null
SN74LV244APWR	null
SN74LV4051APWR	null
SN74LV4052APWR	null
SN74LV595APWR	null
SN74LV595APWRG3	null
SN74LVC00APW	null
SN74LVC04APWR	null
SN74LVC07APWR	null
SN74LVC08APW	null
SN74LVC08APWR	null
SN74LVC125APW	null
SN74LVC125APWR	null
SN74LVC126APWR	null
SN74LVC138APW	null
SN74LVC14APWR	null
SN74LVC157APWR	null
SN74LVC16244ADGGR	null
SN74LVC16245ADGGR	null
SN74LVC16373ADGGR	null
SN74LVC16T245DGGR	null
SN74LVC2244APW	null
SN74LVC244APW	null
SN74LVC244APWR	null
SN74LVC245APW	null
SN74LVC245APWR	null
SN74LVC245APWT	null
SN74LVC257APWR	null

SN74LVC32APWR	null
SN74LVC373APWR	null
SN74LVC374APWR	null
SN74LVC4245APW	null
SN74LVC4245APWR	null
SN74LVC541APW	null
SN74LVC541APWR	null
SN74LVC573APW	null
SN74LVC574APWR	null
SN74LVC8T245PW	null
SN74LVC8T245PWR	null
SN74LVCC3245APW	null
SN74LVCC3245APWR	null
SN74LVCH16245ADGGR	null
SN74LVCH16T245DGGR	null
SN74LVCH8T245PWR	null
SN74LVCHR16245AGR	null
SN74LVCR2245APWR	null
SN74LVT125PW	null
SN74LVT125PWR	null
SN74LVT245BPWR	null
SN74LVTH125PWR	null
SN74LVTH162244DGGR	null
SN74LVTH162245DGGR	null
SN74LVTH16244ADGGR	null
SN74LVTH16245ADGGR	null
SN74LVTH16374DGGR	null
SN74LVTH18512DGGR	null
SN74LVTH244APWR	null
SN74LVTH245APWR	null
SN74LVU04APWR	null
SN74VMEH22501ADGGR	null
SN75C1168PW	null
TCA6416APWR	null
TCA6507PW	null
TCA9539PWR	null
TCA9554APWR	null
TL972IPWR	null
TLC59116IPWR	null
TLC5925IPWR	null
TPD12S016PWR	null
TPD12S521DBTR	null
TRS202EIPW	null
TRS3221ECPW	null
TRS3221ECPWR	null
TRS3221EIPW	null
TRS3221EIPWR	null
TRS3243EIPWR	null
TRS3318ECPW	null
TRS3318ECPWR	null
TRS3318EIPW	null

TRS3318EIPWR	null
TRSF3232EIPW	null
TRSF3232EIPWR	null
TS3A4751PWR	null
TS3A5017PWR	null
TS3A5018PW	null
TUSB1106PWR	null
TXB0104PWR	null
TXB0106PWR	null
TXB0108PWR	null
TXS0104EPWR	null
TXS0108EPWR	null
ULN2003APWR	null
ULN2003LVPWR	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20120822001		<b>PCN Date:</b>	08/31/2012	
<b>Title:</b>	Qualification of Mold Compound 4211471 and Mount Compound 4211470 for Select Devices Assembled in TI-Malaysia and TI-Taiwan using TSSOP package				
<b>Customer Contact:</b>	PCN_ww_admin_team@list.ti.com	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	12/01/2012	<b>Estimated Sample Availability:</b>	Date provided at sample request.		
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
Qualification of Mold Compound 4211471 and Mount Compound 4211470 for Select Devices Assembled in TI-Malaysia and TI-Taiwan using TSSOP package. Devices will remain in their current assembly facility and material differences are shown in the following table:					
		<b>Change From:</b>		<b>Change To:</b>	
<b>Mount Compound</b>		4042500		4211470	
<b>Mold Compound</b>		4209002		4211471	
Qual Results are provided in the Qual Data Section.					
<b>Reason for Change:</b>					
Continuity of supply.					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None.					
<b>Changes to product identification resulting from this PCN:</b>					
None.					
<b>Product Affected:</b>					
Please see page two of this document for your list of PCN affected devices.					
<b>Qualification Data Approved (03/12/2012)</b>					
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.					
<b>Qual Vehicle 1: 20Z45DBTRR1MC (MSL2-260C)</b>					
<b>Package Construction Details</b>					
<b>Assembly Site:</b>	TI Taiwan	<b>Mold Compound:</b>	4211471		
<b># Pins-Designator, Family:</b>	38-DBT, TSSOP	<b>Mount Compound:</b>	4211470		
<b>Lead frame (Finish, Base):</b>	NiPdAu, Cu	<b>Bond Wire:</b>	0.96 Mil Diameter, Au		



<b>Qualification:</b> <input type="checkbox"/> <b>Plan</b> <input checked="" type="checkbox"/> <b>Test Results</b>				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-
Notes: * Preconditioning sequence: Level 2-260C.				
<b>Qual Vehicle 2 : 7A3T16212DGVR (MSL 1-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	56-DGV, TVSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> <b>Plan</b> <input checked="" type="checkbox"/> <b>Test Results</b>				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
Flammability	Method A - UL94V-0	5/0	5/0	5/0
Flammability	Method B - IEC 695-2-2	5/0	5/0	5/0
Flammability	Method C - UL1694	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				
<b>Qual Vehicle 3 : CDCE706PWR (MSL1-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	20-PW, SOIC	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> <b>Plan</b> <input checked="" type="checkbox"/> <b>Test Results</b>				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	Pass	-	-
*High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				

<b>Qual Vehicle 4 : E8722DGG (MSL1-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	64-DDG, TSSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.15 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	
*High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	
Flammability	Method A - UL94V-0	5/0	-	
Flammability	Method B - IEC 695-2-2	5/0	-	
Flammability	Method C - UL1694	5/0	-	
Manufacturability	(per mfg. Site specification)	Pass	Pass	
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	
Notes: * Preconditioning sequence: Level 1-260C.				
<b>Qual Vehicle 5: SN0610001DGGR (MSL2-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Taiwan	Mold Compound:	4211471	
# Pins-Designator, Family:	48-DGG, TSSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
*Biased Temp and Humidity	85C/85%RH (1000 Hrs)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-
Notes: * Preconditioning sequence: Level 2-260C.				
<b>Qual Vehicle 6: SN65C1168PWR (MSL1-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	16-PW, TSSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Cu	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
*Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				

<b>Qual Vehicle 7: SN75976A2DGG (MSL2-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	56-DGG, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.95 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 2-260C.				
<b>Qual Vehicle 8: TAS5086DBT (MSL2-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Taiwan	Mold Compound:	4211471	
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Diameter, Cu	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Steady-state Life Test	140C (480 Hrs)	77/0	77/0	77/0
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +0/-5C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 2-260C.				
<b>Qual Vehicle 9: TCA9539PWR (MSL1-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	24-PW, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.70 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +0/-5C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				

<b>Qual Vehicle 10: TPIC1353DBTRG4 (MSL2-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Taiwan	Mold Compound:	4211471	
# Pins-Designator, Family:	44-DBT, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.31 Mil Diameter, Cu	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Steady-state Life Test	140C (480 Hrs)	77/0	77/0	77/0
*Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +0/-5C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 2-260C.				
<b>Qual Vehicle 11: UCC5672PWPTR (MSL1-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	28-pw, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Au	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +0/-5C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>